

Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MI22-1533	SERIAL NO. 09/754,926		
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT Kie Y. Ahn et al.			
				FILING DATE January 4, 2001	GROUP 2813		
U.S. PATENT DOCUMENTS							
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA						
FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Subclass	Translation
	AB						Yes No
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
	AC		"High Quality Ta _x O _y Gate Dielectrics with T _x < 10 Å"; H.F. Luan, S.J. Lee, C.H. Lee, S.C. Song, Y.L. Mao, Y. Senzaki, D. Roberts, and D.L. Kwong, IEDM, pp. 141-144, 1999.				
<i>EX</i>	AD		Article: "High-K Dielectrics for Giga-Scale CMOS and Non-Volatile Memory Technology", L. Manchanda, G. Alers, and J.P. Han, March 15, 2000.				
<i>EX</i>	AE		Article: "Application of Al _x O _y Grown by Atomic Layer Deposition to DRAM and FeRAM", C.T. Kim, C. Lim, K.M. Kim, M.S. Kim, H.K. Jang, Y.S. Yu and J.S. Roh, pg. 316, March 13, 2000.				
<i>EX</i>	AF		Article: Beam Solid Interactions: Fundamentals and Applications; Materials Research Society Symposium Proceedings; Volume 279; pp. 825-830; Symposium held November 30-December 4, 1992.				
	AG		"Effect of Plasma Activation on the Phase Transformations of Aluminum Oxide"; O. Zywicki, G. Hoetzsch, Surface & Coatings Technology 76-77, 1995; pp. 754-762				
	AH		Article: "Tunability of Intrinsic Stress in SiO _x Dielectric Films Formed By Molecular Beam Deposition"; Naresh Chand, R.R. Kota, J.W. Osenbach, and W.T. Tsang", pp. 195-200, Volume 356, 1995.				
<i>EX</i>	AI		"Optical Thin Films IV: New Developments"; James D. Rancourt; SPIE - The International Society for Optical Engineering; Volume 2262; pp. 14-21; July 1994.				
	AJ						
EXAMINER	<i>Eric Kifer</i>			DATE CONSIDERED	<i>5/8/02</i>		
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							